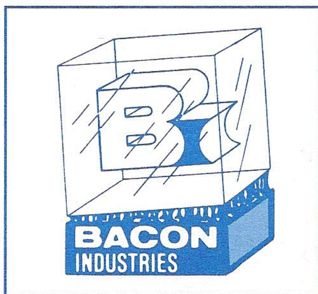

TECHNICAL DATA SHEET

TDS# 1386

DATE: JUNE 2013

BACON INDUSTRIES

MICROCIRCUIT GRADE POTTING COMPOUND P-86

Potting Compound P-86 is a highly filled heat-curing system designed for use in electronic and microcircuit packaging. It is exceptionally fluid, can be handled easily at room temperature, cures in a relatively short time and has excellent electrical properties at high temperatures.

Because Potting Compound P-86 uses a liquid anhydride curing agent, it usually can be used over semiconductor junctions without causing poisoning failure. The costly step of protecting chips with silicone rubber barrier coatings can be eliminated in many applications.

RECOMMENDED MIXING AND HANDLING PARAMETERS

Resin	C-85
Activator	BA-62
Parts by weight of activator required per hundred of adhesive	27.0
Viscosity of Activated Compound, poise	
at 75°F	40.0
at 180°F	3.0
Working Life, hours	
at 75°F	>16
at 180°F	1
Work Life at 180°F, minutes	80
Pot Life (tack-free time) at 180°F, minutes	100
Recommended Cure, hr/°F	4/180
Alternate Cure, hr/°F	2/185 + 3/300

TYPICAL PROPERTIES OF CURED ADHESIVE:

Color	Black
Specific Gravity	1.72
Hardness, Shore D	90
Linear Shrinkage upon cure[1], %	0.16
Flexural Strength[2], psi	12100
Flexural Modulus[2], 10^6 psi	1.6
Water Absorption (24 hours at 77°F), %	0.02
Heat Distortion Temperature[3] (264 psi), °F	185
Glass Transition temperature[3] (Tg) by DSC, °F	165
Coefficient of Thermal Expansion, 10^{-6}/°F	
between -65°F and 80°F	18
between 80°F and 200°F	22

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